

Product / Process Change Notification (PCN)

Notification Date: May 9, 2024

PCN Number: PCN-2401

PCN Title: FSMD-B Fluxless Die Attach Implementation

Product/ Process Identification:

FBG04N30BC
FBG04N30BSH
FBG10N30BC
FBG10N30BSH
FBG20N18BC
FBG20N18BSH
EPC7001BC
EPC7001BSH
EPC7004BC
EPC7004BSH
EPC7007BC
EPC7007BSH
70-003
70-006
70-007
70-008
70-001
70-004
70-020

Description of Change: Flux solder paste will no longer be used in the FSMD-B package type products during manufacturing to boost reliability and enhance yield. This change will not impact the form, fit, or function of the products. The updated process has passed EPCS's qualification successfully. This change will be effective on product listed above beginning with LDC 2419.

Information Requests

If there are any questions, comments or information required regarding this PCN please contact your local EPCS Sales Representative.

EPCS considers this change approved if we do not receive any written objection within 30 days from notification date of this PCN letter. If EPCS receives objection, then EPCS will provide a 90-day transition period from the date of PCN notification.

EPCS Approval

This PCN has been reviewed by EPCS's Quality & Reliability Department:

Product / Process Change Notification (PCN)

Signature: *Hannah Bornt*

Name: Hannah Bornt

Date: 5/9/2024